



INGENIA

Purge Compounds

The use of Ingenia's proprietary purge compounds increases overall efficiency and lowers costs by reducing downtime between color and material changeovers. Moreover, our purge compounds can also extend the life of your processing equipment and reduce waste.

Purge Types

- **Transition purge compounds** are used to clean the extruder and die when transitioning the film structure, changing colours and resins;

- **Shut down purges** are used when the extruder is idle for prolonged periods of time such as holiday and maintenance shut downs.

Where and Why:

- In addition to Blown Film, purge compounds find use in other extrusion processes like cast film, extrusion coating, blow molding and injection molding;
- Use of purge compounds results in lower downtime and quicker transition to the next/new film structure.

IP1851 Transition Purge Compound (use at 100%)

IP1851 is a transition purge compound designed for use in LDPE, LLDPE and HDPE applications to facilitate the rapid purging of the system. It can be used in a variety of applications such as Blown and Cast Film and Blow molding. Specially formulated with scrubbing and release agents to rapidly clean your machinery, IP1851 is excellent for resin changes, colour changes and for use in those rare situations that require manual cleaning of the extrusion line. With IP1851, the bubble can be maintained throughout the purging cycle, significantly reducing downtime and resulting in cost savings.

IP1850 Shutdown Purge Compound (use at 100%)

Ingenia's IP1850 shutdown purge compound helps protect idle machinery, ensuring it remains in a prime state, ready for operation when needed. IP1850 is highly stabilized to reduce oxidation over protracted periods of machine idle time. IP1850 is used after purging the system with IP1851 transition purge. This allows for easy machine startups with minimal degradation.

IP1866 Transition Purge for Nylon / EVOH (use at 100%)

Ingenia's proprietary IP1866 is a transition purge compound specially designed for rapid changeover in Nylon and EVOH multilayer film extrusion. With the rapid purge results you get from our IP1866 purging compound, you will increase the profitability of your operations by significantly reducing downtime, and lowering scrap costs and manufacturing costs. Moreover, the bubble is maintained throughout the purge cycle. IP1866 is non-abrasive, non-corrosive and does not emit any noxious fumes. In short, its use does not harm the operator or the equipment. For optimum results IP1866 is used at 100%.

Learn More

Ingenia's innovative Purging Compounds are technologically advanced to meet current and future demands for an evolving plastics industry. To learn more, contact Evan McDonald at: evanm@ingeniapolymers.com or by phone at: +1 (403) 236-9333 ext: 2038